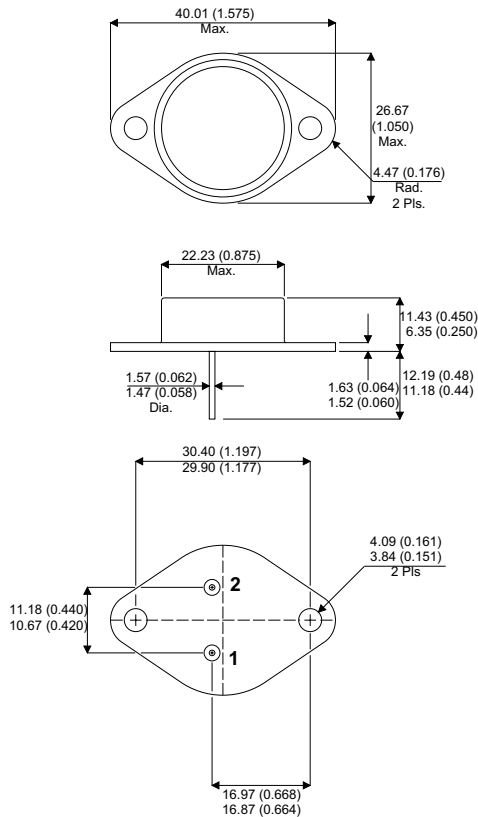


MECHANICAL DATA

Dimensions in mm (inches)



TO-3 Metal Package

Pin 1 – Gate Pin 2 – Source Case – Drain

P-CHANNEL MOSFET IN A TO3 FOR HIGH RELIABILITY APPLICATIONS.

V_{DSS}	100V
I_D	40A
$R_{DS(on)}$	0.07Ω

FEATURES

- FAST SWITCHING
- SCREENING OPTIONS AVAILABLE


ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

V_{GS}	Gate – Source Voltage	±20V
I_D	Continuous Drain Current ($T_{case} = 25^{\circ}C$)	40A
I_D	Continuous Drain Current ($T_{case} = 100^{\circ}C$)	29A
I_{DM}	Pulsed Drain Current ¹	140A
P_D	Power Dissipation	200W
	Linear Derating Factor	1.3W/°C
E_{AS}	Single Pulse Avalanche Energy ²	780mJ
E_{AR}	Repetitive Avalanche Energy ¹	21mJ
T_J, T_{stg}	Operating Junction and Storage Temperature Range	-55 to +150°C
$R_{\theta JC}$	Junction – Case Thermal Resistance	0.75°C/W
$R_{\theta JA}$	Junction – Ambient Thermal Resistance	62°C/W

Notes

- 1) Repetitive rating; pulse width limited by max. junction temperature.
- 2) $V_{DD} = -25V$, $L = 3.5mH$, $R_G = 25\Omega$, $I_{AS} = -21A$, Starting $T_J = 25^{\circ}C$

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
STATIC ELECTRICAL RATINGS					
$V_{(BR)DSS}$	Drain – Source Breakdown Voltage	$V_{GS} = 0V$ $I_D = -250\mu A$	-100		V
$R_{DS(on)}$	Static Drain to Source On Resistance ⁴	$V_{GS} = -10V$ $I_D = -24A$		0.07	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = -250\mu A$	- 2.0	-4.0	V
g_{fs}	Forward Transconductance	$V_{DS} = -8V$ $I_D = -20A$	14		S
I_{DSS}	Drain to Source Leakage Current	$V_{DS} = 100V$ $V_{GS} = 0V$		-25	μA
		$V_{DS} = 100V$ $V_{GS} = 0V$ $T_J = 125^{\circ}C$		-250	
I_{GSS}	Gate to Source Forward Leakage	$V_{GS} = 20V$		100	nA
I_{GSS}	Gate to Source Reverse Leakage	$V_{GS} = -20V$		-100	
DYNAMIC CHARACTERISTICS					
C_{iss}	Input Capacitance	$V_{GS} = 0V$		2700	pF
C_{oss}	Output Capacitance	$V_{DS} = -25V$		790	
C_{riss}	Reverse Transfer Capacitance	$f = 1MHz$		450	
Q_g	Total Gate Charge ⁴	$I_D = -21A$ $V_{DS} = -80V$ $V_{GS} = -10V$			180
Q_{gs}	Gate – Source Charge ⁴				25
Q_{gd}	Gate – Drain (“Miller”) Charge ⁴				97
$t_{d(on)}$	Turn-On Delay Time ⁴	$V_{DD} = -50V$		17	ns
t_r	Rise Time ⁴	$I_D = -21A$		86	
$t_{d(off)}$	Turn-Off Delay Time ⁴	$R_G = 2.5\Omega$		79	
t_f	Fall Time ⁴	$R_G = 2.4\Omega$		81	
SOURCE – DRAIN CHARACTERISTICS					
I_S	Continuous Source Current	MOSFET symbol showing the integral reverse p-n junction 		-40	A
I_{SM}	Pulse Source Current ¹			-140	
V_{SD}	Diode Forward Voltage ⁴	$T_J = 25^{\circ}C$, $I_S = 21A$, $V_{GS} = 0V$		-1.6	V
t_{rr}	Reverse Recovery Time ⁴	$d_i / d_t \leq -100A/\mu s$		170	260
Q_{rr}	Reverse Recovery Charge ⁴	$T_J = 25^{\circ}C$, $I_F = -21A$		1.2	1.8
t_{on}	Forward Turn-On Time	negligible			—
PACKAGE CHARACTERISTICS					
L_D	Internal Drain	Between lead, 6mm(0.25in.) from package and center of die contact		4.5	nH
L_S	Internal Source Inductance			7.5	

Notes

- 1) Repetitive rating; pulse width limited by max. junction temperature.
- 2) $V_{DD} = -25V$, $L = 3.5mH$, $R_G = 25\Omega$, $I_{AS} = -21A$, Starting $T_J = 25^{\circ}C$
- 3) $I_{SD} \leq -6.5A$, $di/dt \leq -100A/\mu s$, $V_{DD} \leq BV_{DSS}$, $T_J \leq 150^{\circ}C$, Suggested $R_G = 7.5\Omega$
- 4) Pulse Test: Pulse Width $\leq 300ms$, $\delta \leq 2\%$